



Product data sheet

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MSNUP2105LT1G HF 🧟

Semiconductor Compiance

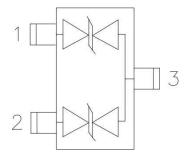


Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

SOT-23

Pin Configuration



Mechanical Characteristics

- Package: SOT-23
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7inch

Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20µs)	Ррр	300	W	
ESD per IEC 61000-4-2 (Air)	N	±30	Ku.	
ESD per IEC 61000-4-2 (Contact)	V _{ESD}	± 30	Kv	
Operating Temperature Range	TJ	-55 to +125	°C	
Storage Temperature Range	T _{STJ}	-55 to +150	°C	



Electrical Characteristics(TA=25°C unless otherwise specified)

P/N	V _{RWM} (V)	Vbr (V)	l⊤ (mA)	Vc @1A	(Max)	/c (@A)	l _ℝ μΑ (Max)	C (Pf) (Typ.)
MSNUP2105LT1G	24	27	1	40	45	5	0.2	25

Characteristic Curves

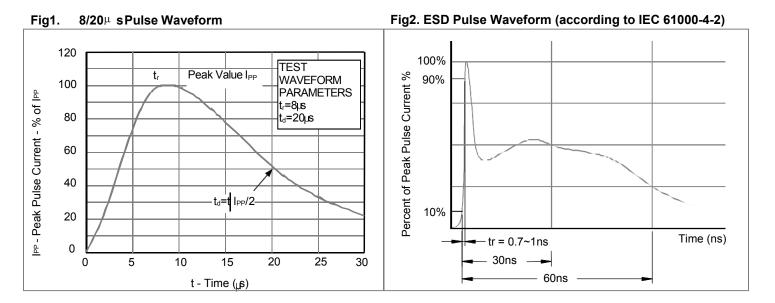
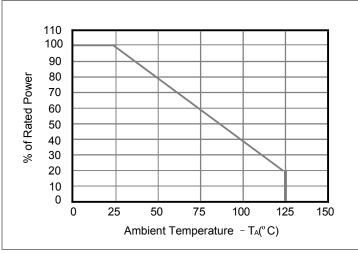


Fig3. Power Derating Curve

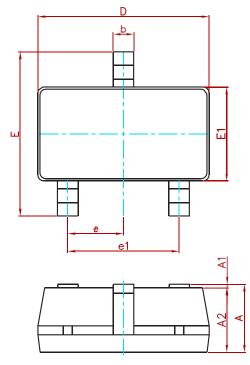


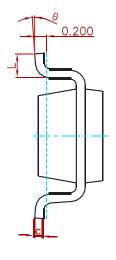


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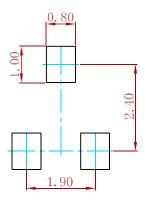
PACKAGE MECHANICAL DATA





Symbol	Symbol Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
e	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
0	0°	8°	0°	8°	

Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MSNUP2105LT1G	SOT-23	3000



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